

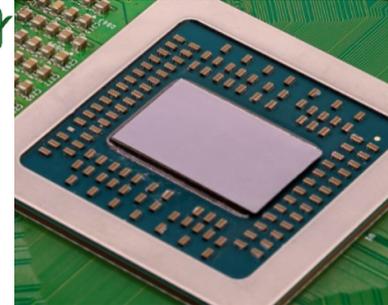


# Phase Change Thermal Interface Material PCM 21-745



## FEATURES & BENEFITS

- Low Thermal Resistance
- RoHS Compliant
- Phase Change ~ 50 °C
- Excellent Interface Wettability
- High Reliability
- Form:Pad



## APPLICATIONS

- CPUs (Notebooks,Desktops, Servers)
- Chipsets
- GPUs
- ASICs Chips
- Smart Phones
- Form:Pad

JONES PCM 21-745, phase change interface thermal material, is designed to maximize heat sink performance and improve component reliability. It minimizes thermal resistance at interfaces and maintains excellent performance when it fills interfacial gaps and voids.

At room temperature, JONES PCM 21-745 is solid and easy to handle. This allows it to be consistently and cleanly applied as dry pad to heat sink or component surface. Upon reaching its softening temperature of 50 °C, PCM 21-745 begins to soften and flow, filling the microscopic irregularities of the component. The result is an interface with minimal bond-line thickness and thermal contact resistance.



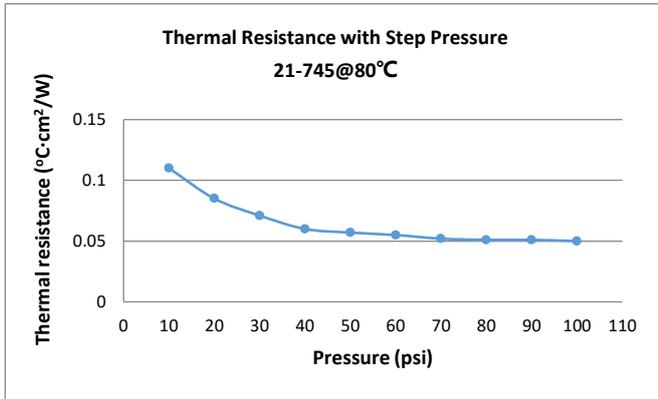
## TYPICAL PROPERTIES

Properties		21-745	Test Method
Thermal	Thermal Conductivity (W/m·K)	5.8	Hot Disk
		4.4	ASTM D5470
	Thermal Resistance (°C·cm <sup>2</sup> /W)	0.060	ASTM D5470
	Phase Change Softening Temp. (°C)	~50	ASTM D3418
	Operation Temperature Range. (°C)	-40~125	JONES Test Method
Physical	Color	Grey	Visual
	Standard Thickness (mm)	0.20-1.00	ASTM D374
	Density (g/cm <sup>3</sup> )	2.6	ASTM D792
Electrical	Volume Resistivity (Ohm·cm)	10 <sup>12</sup>	ASTM D257
	Surface Insulation Resistance (Ohm)	10 <sup>8</sup>	IPC-TM-650
Regulatory	Flammability Rating	V0	UL 94



## TEST RESULTS

### Thermal Resistance



### PART NUMBER SYSTEM

**21 - 7 45    AB - YYY**  
 ①    ②    ③        ④        ⑤

- ① 21-Thermal management material
- ② 7- Phase Change Material
- ③ 45- Thermal Conductivity 4.0W/m·K
- ④ AB- Optional style
- ⑤ YYY- Thickness



### ORDERING INFORMATION

**Standard Packaging:**  
Customizable packaging

**Storage Requirement**  
10° to 30°C, <65%RH, sealing preservation  
12 months from date of manufacture.  
\* Unopened Original Package

#### HANDLING PRECAUTIONS

**FOR SAFE HANDLING INFORMATION OF THIS PRODUCT, PLEASE CONTACT WITH YOUR JONES REPRESENTATIVE FOR THE SAFETY DATA SHEET (SDS).**

#### LIMITED WARRANTY INFORMATION

The information provided in this Technical Data Sheet including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the data of this TDS. Jones Corp is not, therefore, liable for the suitability of any Jones Corp products for any specific or general uses. Jones Corp shall not be liable for incidental or consequential damages of any kind.

#### FOR MORE INFORMATION

About our high performance materials, solutions and capabilities, please visit our website:

<http://www.jones-corp.com>

#### Disclaimer

- The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the issuing date of this TDS. When using our products, no matter what type of equipment they might be used for, be sure to make a written agreement on the specifications with us in advance. The design and specifications in this TDS are subject to change without prior notice.
- Do not use the products beyond the specifications described in this TDS. This TDS explains the typical performance of the products as individual component. Before use, check and evaluate their operations when installed in your products.
- The product provided in this TDS compliance with HSF.

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